SCOPE:

This specification applies to the Pb Free high current type SMD inductors for

MSCDRI-6015X-SERIES

Warn:It is here not to use synchronous rectification circuit!

PRODUCT INDENTIFICATION

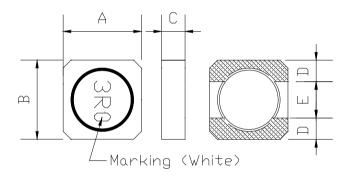
MSCDRI - 6015X - 3R0 M

(I)

2

- 3) 4
- 1 Product Code
- **② Dimensions Code**
- **3 Inductance Code**
- **4** Tolerance Code

(1) SHAPES AND DIMENSIONS



A: 6.0±0.2 mm

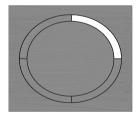
B: 6.0±0.2 mm

C: 1.5 Max. mm

D: 2.0 Typ. mm

E: 2.0 Typ. mm

Void Appearance Tolerance Limit



- 1. The length of the hole in the epoxy of the sealed glue position should be less than 1/4 of the DR core 's circumference, otherwise, it is NG.
- 2. The total length of the amount of hole in the epoxy should be less than 1/4 of the DR core 's circumference, otherwise, it is NG.

(2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

L : HP 4284A PRECISION LCR METER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)



TABLE 1

MAGLAYERS	Inductance	Percent	Test	Resistance	Rated DC Current		Marking
PT/NO.	L(µH)	Tolerance	Frequency	RDC(Ω)Max.	IDC1(A)	IDC2(A)	Warking
MSCDRI-6015X-3R0□	3.0	N	100kHz/0.1V	65m	2.20	2.10	3R0
MSCDRI-6015X-3R3	3.3	N	100kHz/0.1V	75m	2.10	2.00	3R3
MSCDRI-6015X-3R6□	3.6	N	100kHz/0.1V	80m	2.00	1.90	3R6
MSCDRI-6015X-6R8	6.8	M,N	100kHz/0.1V	0.130	1.60	1.40	6R8

※ ☐ specify the inductance tolerance,M(±20%),N(±30%)

% IDC1 : Based on inductance change (\triangle L/Lo : drop 30% Max.) @ ambient temp. 25 $^{\circ}$ C

IDC2: Based on temperature rise ($\triangle T$: 40°C TYP.)

Rated DC Current: The less value which is IDC1 or IDC2.



(4) RELIABILITY TEST METHOD MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS			
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		in figure 1 and a load applied unitil the figure in the arrow			
	There shall be	direction is made approximately 3mm.(keep time 30 seconds)			
	no mechanical	PCB dimension shall the page 7/9			
	damage or elec-	F(Pressurization)			
	trical damage.	\Box			
		R5 45±2 45±2 10 20 R340			
		PRESSURE ROD figure-1			
Vibration	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		and when a vibration having an amplitude of 1.52mm			
	There shall be	and a frequency of from 10 to 55Hz/1 minute repeated should			
	no mechanical	be applied to the 3 directions (X,Y,Z) for 2 hours each.			
	damage.	(A total of 6 hours)			
Solderability	New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated			
	More than 90%	over the whole of the sample before hard, the sample shall			
		then be preheated for about 2 minutes in a temperature of			
		130~150℃ and after it has been immersed to a depth 0.5mm			
		below for 3±0.2 seconds fully in molten solder M705 with a temperature of 245±5°C.			
		More than 90% of the electrode sections shall be couered			
		with new solder smoothly when the sample is taken out of			
		the solder bath.			
		Section Marin			



MECHANICAL

TEST ITEM	SPECIFICATION					
TEST ITEM Istance to The stance to not not not not not not not not not	Temperature profile of reflow soldering Soldering					
	The specimen shall be passed through th condition shown in the above profile for 1					

ELECTRICAL

TEST ITEM	SPECIFICATION	TEST DETAILS		
Temperature	∆L/L20°C ≦±10%	The test shall be performed after the sample has stabilized in		
characteristics	0~2000 ppm/°C	an ambient temperature of -20 to +85 $^{\circ}\mathrm{C}$,and the value		
		calculated based on the value applicable in a normal		
		temperature and narmal humidity shall be △L/L20°C ≦±10%.		

ENVIROMENT CHARACTERISTICS

TEST ITEM				SPECIFICATION			
High temperature	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in an atmospere with					
storage		a temperature of 125 $^{\circ}\!$					
	There shall be	Upon completion of the measurement shall be made after the					
	no mechanical	sample has been left in a normal temperature and normal					
	damage.	humidity for 1 hour.					
Low temperature	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in an atmosphere with					
storage		a temperature of -25±3℃.					
	There shall be	Upon completion of the test, the measurement shall be made					
	no mechanical	after the sample has been left in a normal temperature and					
	damage.	normal humidity for 1 hour.					
Change of	∆L/Lo≦±5%	The sample shall be subject to 5 continuos cycles, such as shown					
temperature		in the ta	ble 2	below and then it shall	be subjected to stand	ard	
	There shall be	atmospheric conditions for 1 hour, after which measurement					
	no other dama-	shall be made.					
	ge of problems						
		table 2				1	
				Temperature	Duration		
			1	−25±3 ℃	30 min.		
				(Themostat No.1)			
		2	Standard	5 sec. or less			
				atmospheric	No.1→No.2		
			3	85±2℃	30 min.		
				(Themostat No.2)			
			4	Standard	5 sec. or less		
				atmospheric	No.2→No.1		
Moisture storage	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in a temperature of					
•		40±2°C and a humidity(RH) of 90∼95%.					
	There shall be	Upon completion of the test, the measurement shall be made after the sample has been left in a normal temperature and					
	no mechanical						
	damage.	normal humidity more than 1 hour.					
Test conditions :							
The sar	nple shall be reflow	soldered	lonto	the printed circuit boa	rd in every test.		



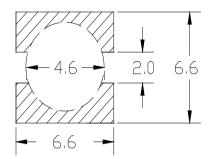
(5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

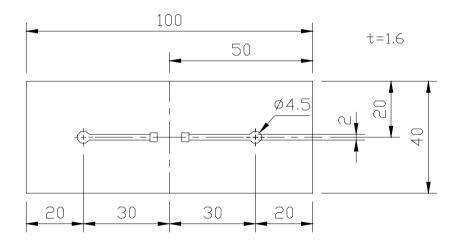
(5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN)

Unit:mm

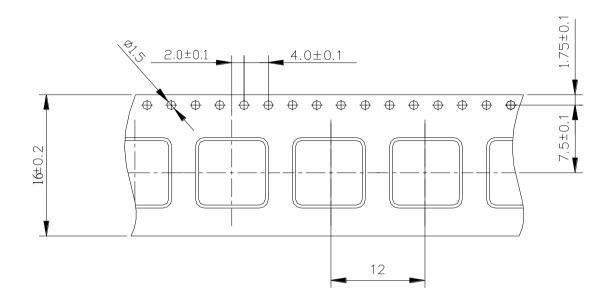


(5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD

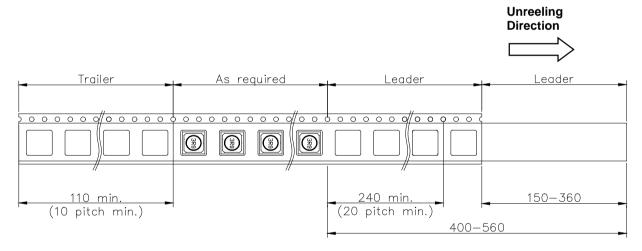


(6) PACKAGING

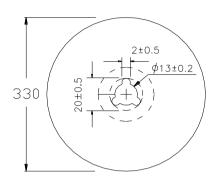
(6)-1 CARRIER TAPE DIMENSIONS (mm)

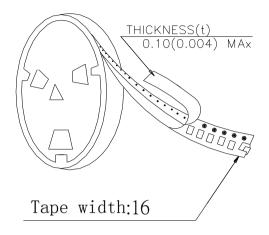


(6)-2 TAPING DIMENSIONS (mm)



(6)-3 REEL DIMENSIONS (mm)





(6)-4 QUANTITY

2000pcs/Reel

The products are packaged so that no damage will be sustained.

